

Features

- Planar Die Construction
- Ultra-Small Surface Mount Package
- Ideally Suited for Automated Assembly Processes
- **Lead, Halogen and Antimony Free, RoHS Compliant (Note 1)**
- **"Green" Device (Note 2)**
- **Qualified to AEC-Q101 Standards for High Reliability**

Mechanical Data

- Case: SOD323
- Case Material: Molded Plastic. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Matte Tin Finish annealed over Alloy 42 leadframe (Lead Free Plating). Solderable per MIL-STD-202, Method 208
- Polarity: Cathode Band
- Weight: 0.0049 grams (approximate)

SOD323



Top View

Ordering Information (Note 3)

Part Number	Case	Packaging
(Type Number)-7-F*	SOD323	3000/Tape & Reel

*Add "-7-F" to the appropriate type number in Electrical Characteristics Table, example: 6.2V Zener – BZT52C6V2S-7-F.

- Notes:
1. No purposefully added lead. Halogen and Antimony Free.
 2. Product manufactured with Data Code V9 (week 33, 2008) and newer are built with Green Molding Compound. Product manufactured prior to Date Code V9 are built with Non-Green Molding Compound and may contain Halogens or Sb₂O₃ Fire Retardants.
 3. For packaging details, go to our website at <http://www.diodes.com>.

Marking Information



xx = Product Type Marking Code
(See Electrical Characteristics Table)

Maximum Ratings @T_A = 25°C unless otherwise specified

Single phase, half wave, 60Hz, resistive or inductive load.
For capacitance load, derate current by 20%.

Characteristic	Symbol	Value	Unit
Forward Voltage (Note 4) @ I _F = 10mA	V _F	0.9	V

Thermal Characteristics

Characteristic	Symbol	Value	Unit
Power Dissipation (Note 5)	P _D	200	mW
Thermal Resistance, Junction to Ambient Air (Note 5)	R _{θJA}	625	°C/W
Operating and Storage Temperature Range	T _J , T _{STG}	-65 to +150	°C

Electrical Characteristics @T_A = 25°C unless otherwise specified

Type Number	Marking Code	Zener Voltage Range (Note 4)				Maximum Zener Impedance f = 1kHz			Maximum Reverse Current (Note 4)		Temperature Coefficient of Zener Voltage @ I _{ZT} = 5mA mV/°C	
		V _Z @ I _{ZT}			I _{ZT}	Z _{ZT} @ I _{ZT}	Z _{ZK} @ I _{ZK}	I _{ZK}	I _R	@ V _R	Min	Max
		Nom (V)	Min (V)	Max (V)	(mA)	Ω	mA	μA	V			
BZT52C2V0S	WY	2.0	1.91	2.09	5	100	600	1.0	150	1.0	-3.5	0
BZT52C2V4S	WX	2.4	2.20	2.60	5	100	600	1.0	50	1.0	-3.5	0
BZT52C2V7S	W1	2.7	2.5	2.9	5	100	600	1.0	20	1.0	-3.5	0
BZT52C3V0S	W2	3.0	2.8	3.2	5	95	600	1.0	10	1.0	-3.5	0
BZT52C3V3S	W3	3.3	3.1	3.5	5	95	600	1.0	5	1.0	-3.5	0
BZT52C3V6S	W4	3.6	3.4	3.8	5	90	600	1.0	5	1.0	-3.5	0
BZT52C3V9S	W5	3.9	3.7	4.1	5	90	600	1.0	3	1.0	-3.5	0
BZT52C4V3S	W6	4.3	4.0	4.6	5	90	600	1.0	3	1.0	-3.5	0
BZT52C4V7S	W7	4.7	4.4	5.0	5	80	500	1.0	2	2.0	-3.5	0.2
BZT52C5V1S	W8	5.1	4.8	5.4	5	60	480	1.0	1	2.0	-2.7	1.2
BZT52C5V6S	W9	5.6	5.2	6.0	5	40	400	1.0	3	2.0	-2.0	2.5
BZT52C6V2S	WA	6.2	5.8	6.6	5	10	150	1.0	2	4.0	0.4	3.7
BZT52C6V8S	WB	6.8	6.4	7.2	5	15	80	1.0	1	4.0	1.2	4.5
BZT52C7V5S	WC, BF	7.5	7.0	7.9	5	15	80	1.0	0.7	5.0	2.5	5.3
BZT52C8V2S	WD	8.2	7.7	8.7	5	15	80	1.0	0.5	5.0	3.2	6.2
BZT52C9V1S	WE	9.1	8.5	9.6	5	15	100	1.0	0.2	6.0	3.8	7.0
BZT52C10S	WF	10	9.4	10.6	5	20	150	1.0	0.1	7.0	4.5	8.0
BZT52C11S	WG	11	10.4	11.6	5	20	150	1.0	0.1	8.0	5.4	9.0
BZT52C12S	WH	12	11.4	12.7	5	25	150	1.0	0.1	8.0	6.0	10.0
BZT52C13S	WI	13	12.4	14.1	5	30	170	1.0	0.1	8.0	7.0	11.0
BZT52C15S	WJ	15	13.8	15.6	5	30	200	1.0	0.1	10.5	9.2	13.0
BZT52C16S	WK	16	15.3	17.1	5	40	200	1.0	0.1	11.2	10.4	14.0
BZT52C18S	WL	18	16.8	19.1	5	45	225	1.0	0.1	12.6	12.4	16.0
BZT52C20S	WM	20	18.8	21.2	5	55	225	1.0	0.1	14.0	14.4	18.0
BZT52C22S	WN	22	20.8	23.3	5	55	250	1.0	0.1	15.4	16.4	20.0
BZT52C24S	WO	24	22.8	25.6	5	70	250	1.0	0.1	16.8	18.4	22.0
BZT52C27S	WP	27	25.1	28.9	2	80	300	0.5	0.1	18.9	21.4	25.3
BZT52C30S	WQ	30	28.0	32.0	2	80	300	0.5	0.1	21.0	24.4	29.4
BZT52C33S	WR	33	31.0	35.0	2	80	325	0.5	0.1	23.1	27.4	33.4
BZT52C36S	WS	36	34.0	38.0	2	90	350	0.5	0.1	25.2	30.4	37.4
BZT52C39S	WT	39	37.0	41.0	2	130	350	0.5	0.1	27.3	33.4	41.2

Notes: 4. Short duration pulse test used to minimize self-heating effect.
3. Part mounted on FR-4 PC board with recommended pad layout, as per <http://www.diodes.com>.

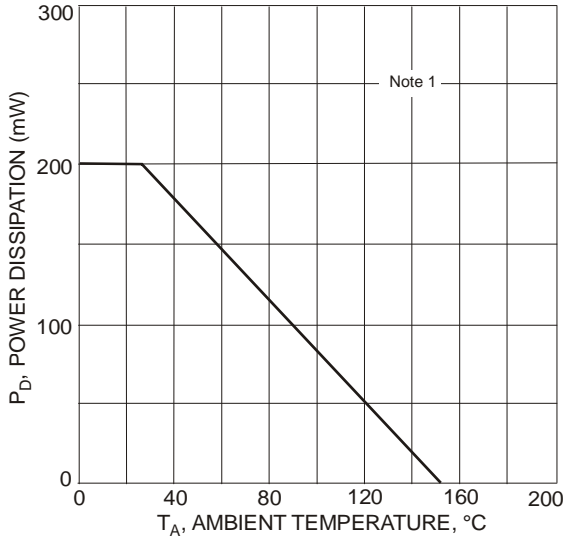


Fig. 1 Power Derating Curve

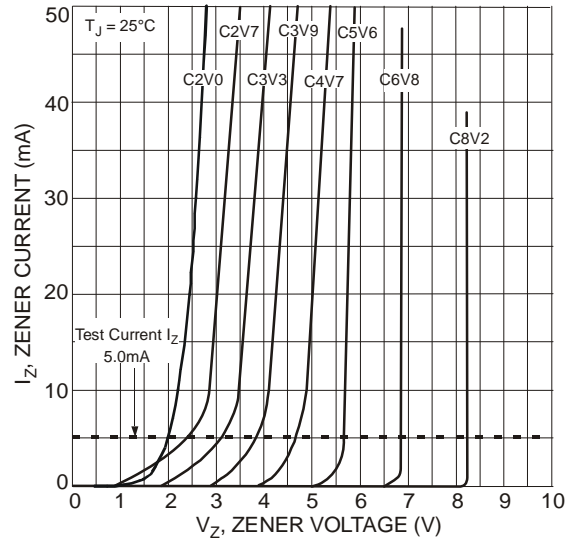


Fig. 2 Typical Zener Breakdown Characteristics

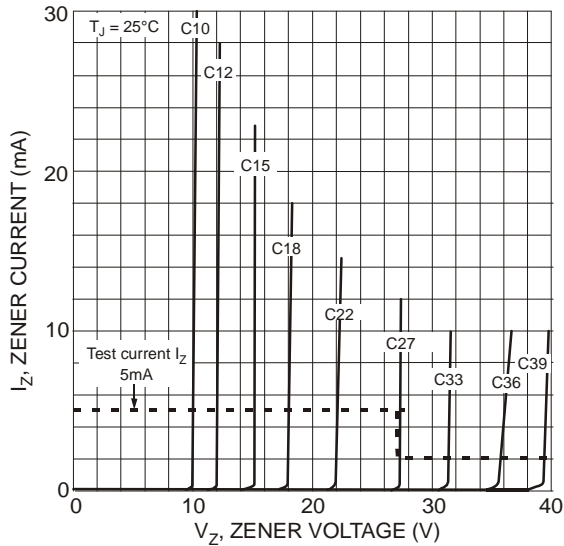


Fig. 3 Typical Zener Breakdown Characteristics

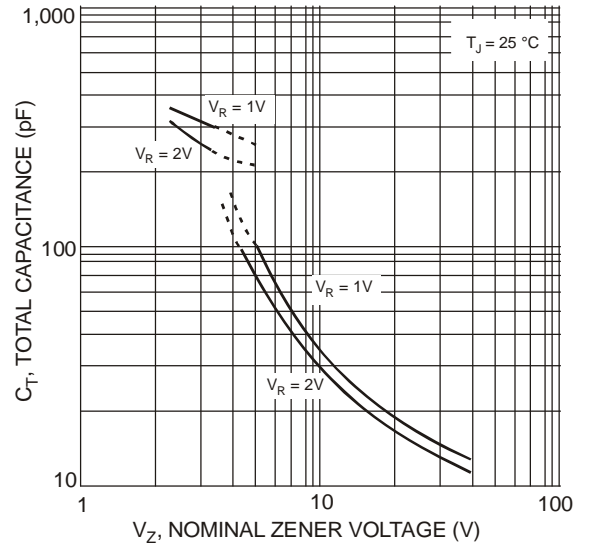
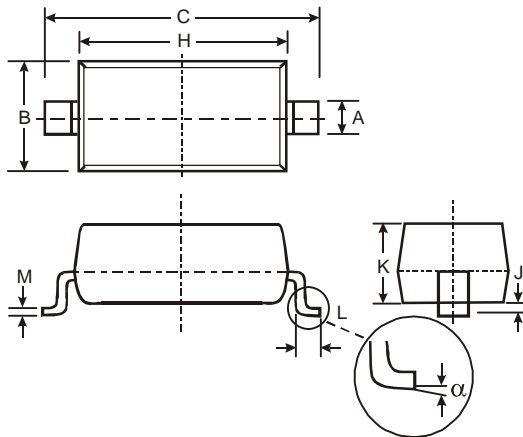


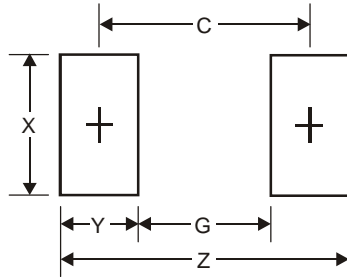
Fig. 4 Typical Total Capacitance vs. Nominal Zener Voltage

Package Outline Dimensions



SOD323		
Dim	Min	Max
A	0.25	0.35
B	1.20	1.40
C	2.30	2.70
H	1.60	1.80
J	0.00	0.10
K	1.0	1.1
L	0.20	0.40
M	0.10	0.15
α	0°	8°
All Dimensions in mm		

Suggested Pad Layout



Dimensions	Value (in mm)
Z	3.75
G	1.05
X	0.65
Y	1.35
C	2.40

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